

N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C	
	6mΩ @ V _{GS} = 10V		
30V	10mΩ @ V _{GS} = 4.5V	55.6A	

Features and Benefits

- Low R_{DS(ON)} Ensures On-State Losses are Minimized
- Excellent $Q_{GD} \times R_{DS(ON)}$ Product (FOM)
- Advanced Technology for DC-DC Converters
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- 100% UIS (Avalanche) Rated
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

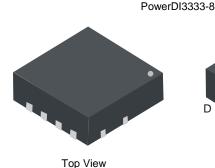
Description and Applications

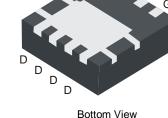
This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

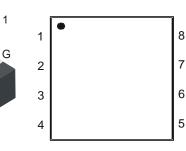
- Backlighting
- Power Management Functions
- DC-DC Converters

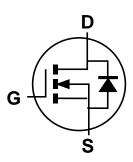
Mechanical Data

- Case: PowerDI[®]3333-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Weight: 0.072 grams (Approximate)









Top View

Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMT3006LFG-7	PowerDI3333-8	2,000/Tape & Reel
DMT3006LFG-13	PowerDI3333-8	3,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



SK1 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	30	V	
Gate-Source Voltage	V_{GSS}	±20	V	
Continuous Drain Current (Note 6) V _{GS} = 10V	$T_C = +25$ °C $T_C = +70$ °C	I _D	55.6 44.4	А
Continuous Drain Current (Note 5) $V_{GS} = 10V$ $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$		I _D	16.0 12.8	А
Maximum Continuous Body Diode Forward Current (Note 5)	I _S	2	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	80	Α	
Avalanche Current, L=0.1mH	I _{AS}	25	Α	
Avalanche Energy, L=0.1mH	E _{AS}	31	mJ	

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	$T_C = +25^{\circ}C$	P_{D}	27.8	W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	4.5	°C/W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	54	C/VV
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}		_	1	μΑ	$V_{DS} = 24V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = +20V, V_{DS} = 0V$ $V_{GS} = -16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1.0	_	3.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance			4.8	6	mΩ	$V_{GS} = 10V, I_D = 12A$	
Static Dialit-Source Off-Resistance	R _{DS(ON)}	-	6.9	10		$V_{GS} = 4.5V, I_D = 12A$	
Diode Forward Voltage	V_{SD}		0.7	1.0	V	$V_{GS} = 0V, I_{S} = 2A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	1,155	_		V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	456	_	pF		
Reverse Transfer Capacitance	Crss		72	_			
Gate Resistance	R_{G}		1.6	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_G	_	8.4	_			
Total Gate Charge (V _{GS} = 10V)	Q_{G}		16.7	_	nC	V _{DD} = 15V. I _D = 9A	
Gate-Source Charge	Q_{GS}		2.2	_	iiC	VDD = 13V, ID = 9A	
Gate-Drain Charge	Q_{GD}		3.5	_			
Turn-On Delay Time	t _{D(ON)}		3.5	_		$V_{DD} = 15V, V_{GS} = 10V,$ $R_G = 3\Omega, I_D = 9A$	
Turn-On Rise Time	t _R		5.5	_	ns		
Turn-Off Delay Time	t _{D(OFF)}	_	13.5	_	115		
Turn-Off Fall Time	t _F	_	4.6	_			
Body Diode Reverse Recovery Time	t _{RR}	_	19.3		ns I 4.5A divite 400A/co		
Body Diode Reverse Recovery Charge	Q_{RR}		8.6	_	nC	$I_F = 1.5A$, di/dt = 100A/ μ s	

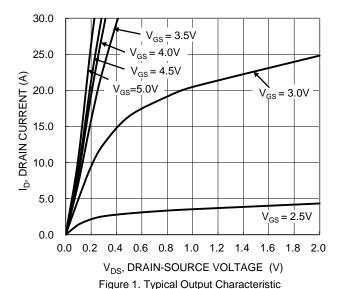
Notes: 5. $R_{\theta JA}$ is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.

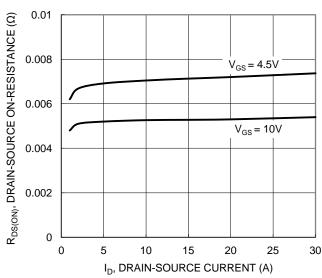
^{6.} Thermal resistance from junction to soldering point (on the exposed drain pad).

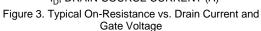
^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to product testing.









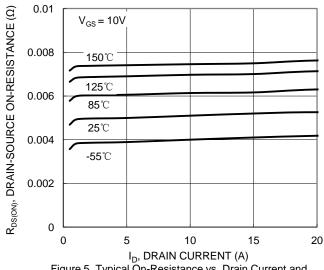
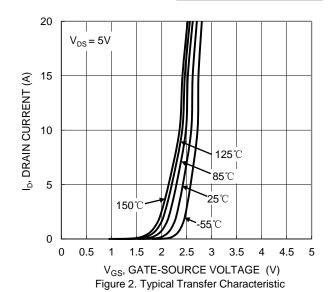


Figure 5. Typical On-Resistance vs. Drain Current and Temperature



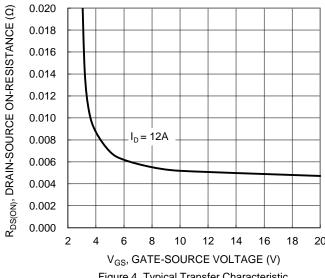


Figure 4. Typical Transfer Characteristic

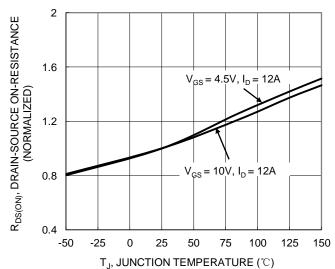


Figure 6. On-Resistance Variation with Temperature



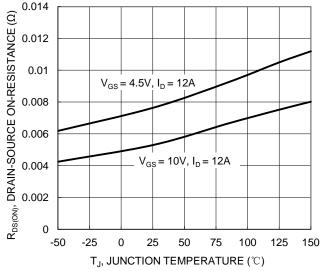
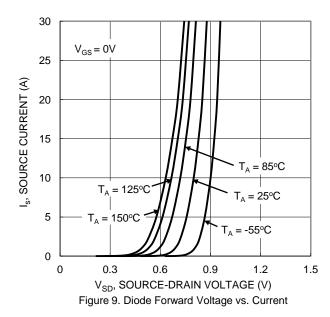


Figure 7. On-Resistance Variation with Temperature



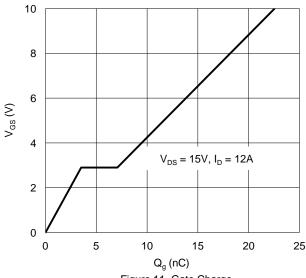


Figure 11. Gate Charge

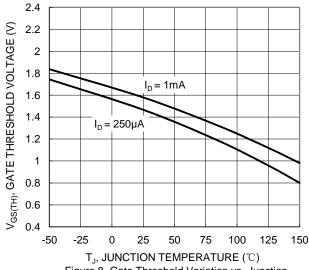
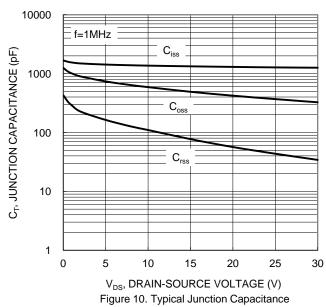


Figure 8. Gate Threshold Variation vs. Junction Temperature



100 ____ =100µs R_{DS(ON)} Limited 10 ID, DRAIN CURRENT (A) P_W =10ms $T_{J(Max)} = 150^{\circ}C$ 0.1 T_C = 25°C Single Pulse DUT on 1*MRP Board $V_{GS} = 10V$ 0.01 0.01 0.1 10 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area



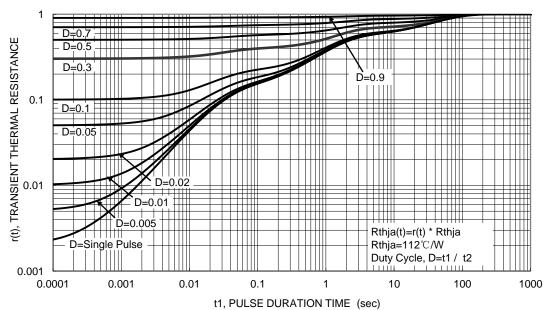


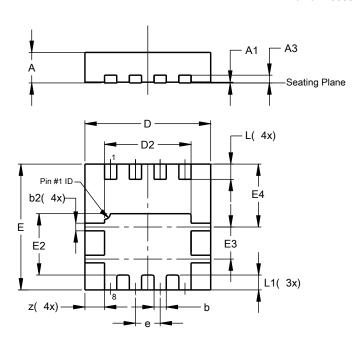
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8

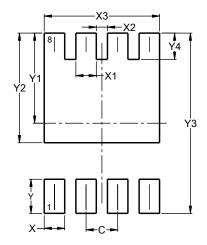


PowerDI3333-8					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
A3	_	_	0.203		
b	0.27	0.37	0.32		
b2	0.15	0.25	0.20		
D	3.25	3.35	3.30		
D2	2.22	2.32	2.27		
Е	3.25	3.35	3.30		
E2	1.56	1.66	1.61		
E3	0.79	0.89	0.84		
E4	1.60	1.70	1.65		
е		_	0.65		
L	0.35	0.45	0.40		
L1	_	_	0.39		
Z	_	_	0.515		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8



Dimensions	Value (in mm)		
С	0.650		
X	0.420		
X1	0.420		
X2	0.230		
Х3	2.370		
Y	0.700		
Y1	1.850		
Y2	2.250		
Y3	3.700		
Y4	0.540		



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